



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

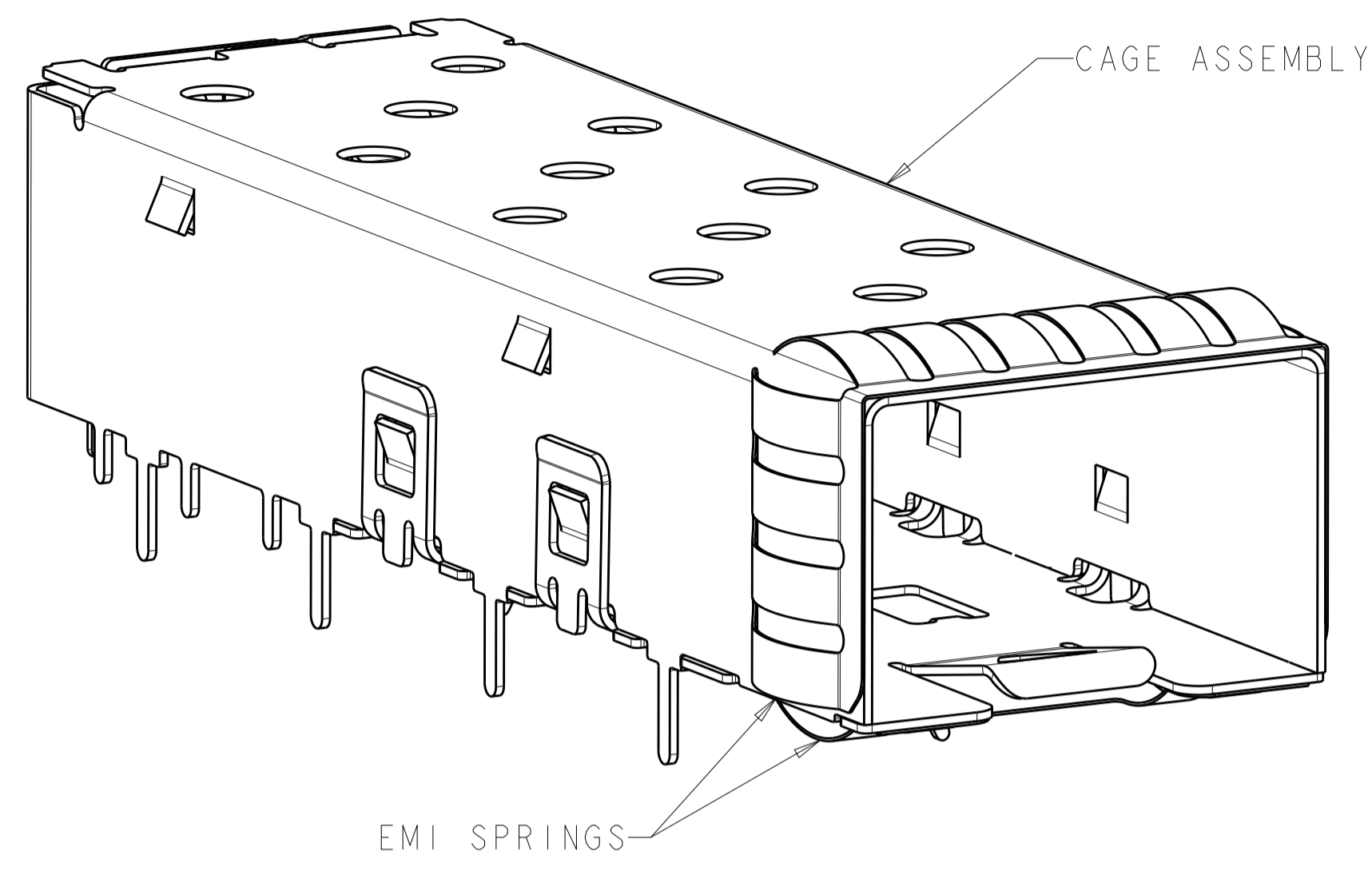
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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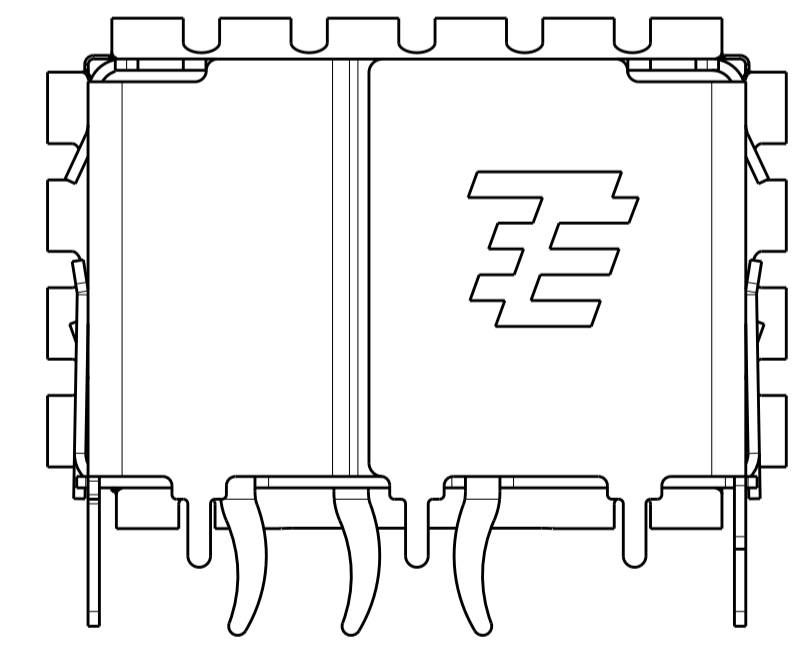
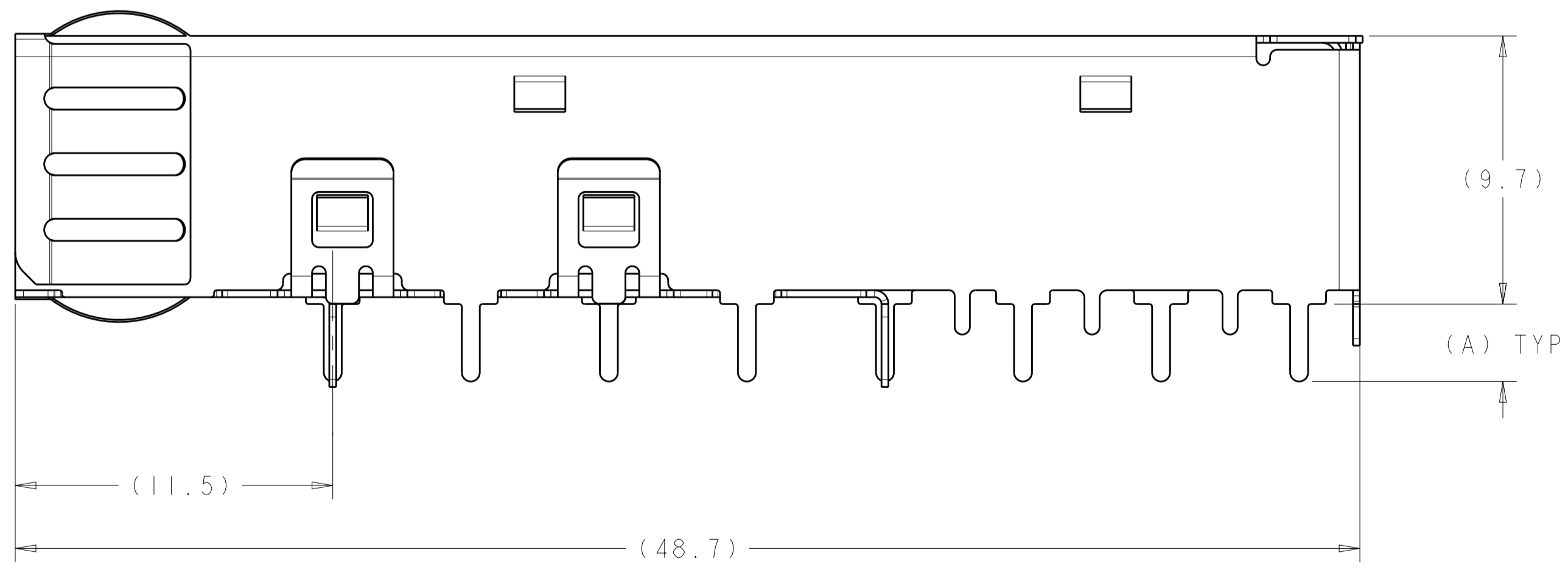
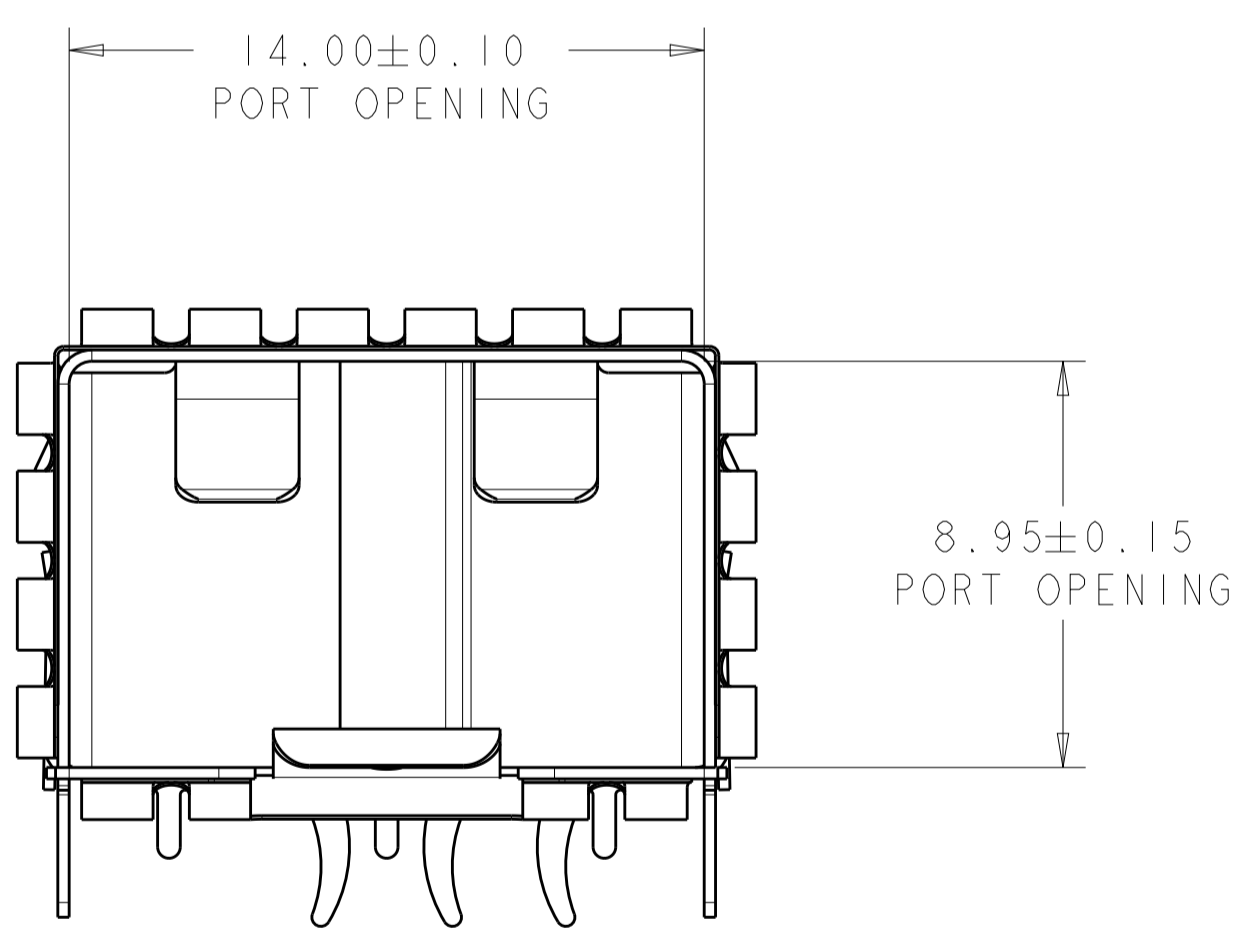
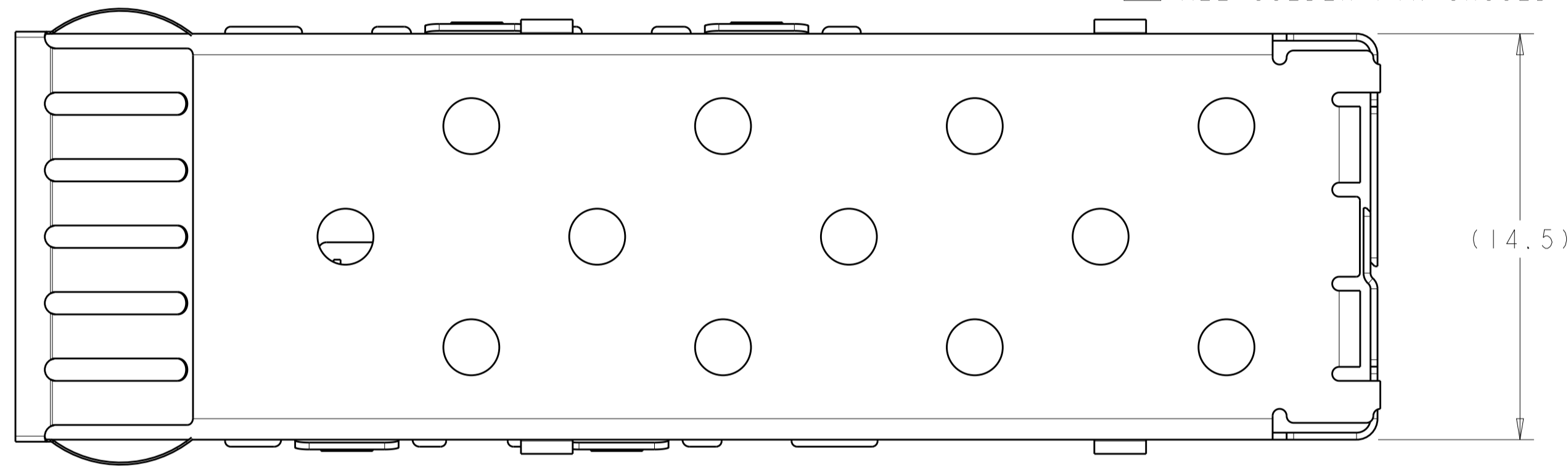
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DMN	APVD
		D1		REVISED PER ECO-13-014703	22SEP2013	PP	SH
		D2		REVISED PER ECO-14-008091	13MAY2014	PP	SH
		D3		REVISED PER ECO-15-000306	08JAN2015	PP	SH
		D4		REVISED PER ECO-15-013454	16SEP2015	pp	SH



- 1 MATERIAL:
CAGE - NICKEL SILVER ALLOY 0.25 THK.
EMI SPRINGS - COPPER ALLOY
- 2 FINISH:
2110304-5 CAGE - 1.27um MIN TIN OF SOLDER TAIL
EMI SPRINGS - 0.8um MIN MATTE TIN OVER 0.8um MIN NICKEL
NON-PLATED EDGES PERMISSIBLE.
- 3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
- 5 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 6. MINIMUM PC BOARD THICKNESS:
SINGLE SIDED = 1.50 mm.
- 7. NOTE DELETED
- 8 PACKAGE TYPE IS TAPE AND REEL.
- 9 FOR ESD PROTECTION TAPE AND REEL PACKAGE ONLY.
MATERIALS(COVER TAPE,EMBOSS TAPE,REEL, INNER LABEL ON REEL) USED WITH AN EPA AREA
MUST PRIMARILY BE ELECTROSTATIC CONDUCTIVE OR ELECTROSTATIC DISSIPATIVE.
NO MATERIAL SHOULD BE CHARGED UP TO MORE THAN 100 VOLTS.
- 10 ALL SOLDER PIN SHOULD BE TIN DIPPED.



8	2.00	2110304-8
10, 9	1.20	2110304-7
10, 9	2.80	2110304-6
8	2.80	2110304-5
	2.00	2110304-3
	2.80	2110304-1
	DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DMN	C. ROHLER	13FEB2009
mm	0 PLC ±0.1	CHK	M. SCHMITT	13FEB2009
	1 PLC ±0.5	APVD	B. WERTZ	13FEB2009
	2 PLC ±0.5	PRODUCT SPEC		
	3 PLC ±0.5	APPLICATION SPEC		
	4 PLC ±0.13	114-13120		
	ANGLES ±0.13	WEIGHT		
MATERIAL	FINISH	Customer Drawing	SCALE	1:1
			SHEET	1 OF 4
			REV	D4

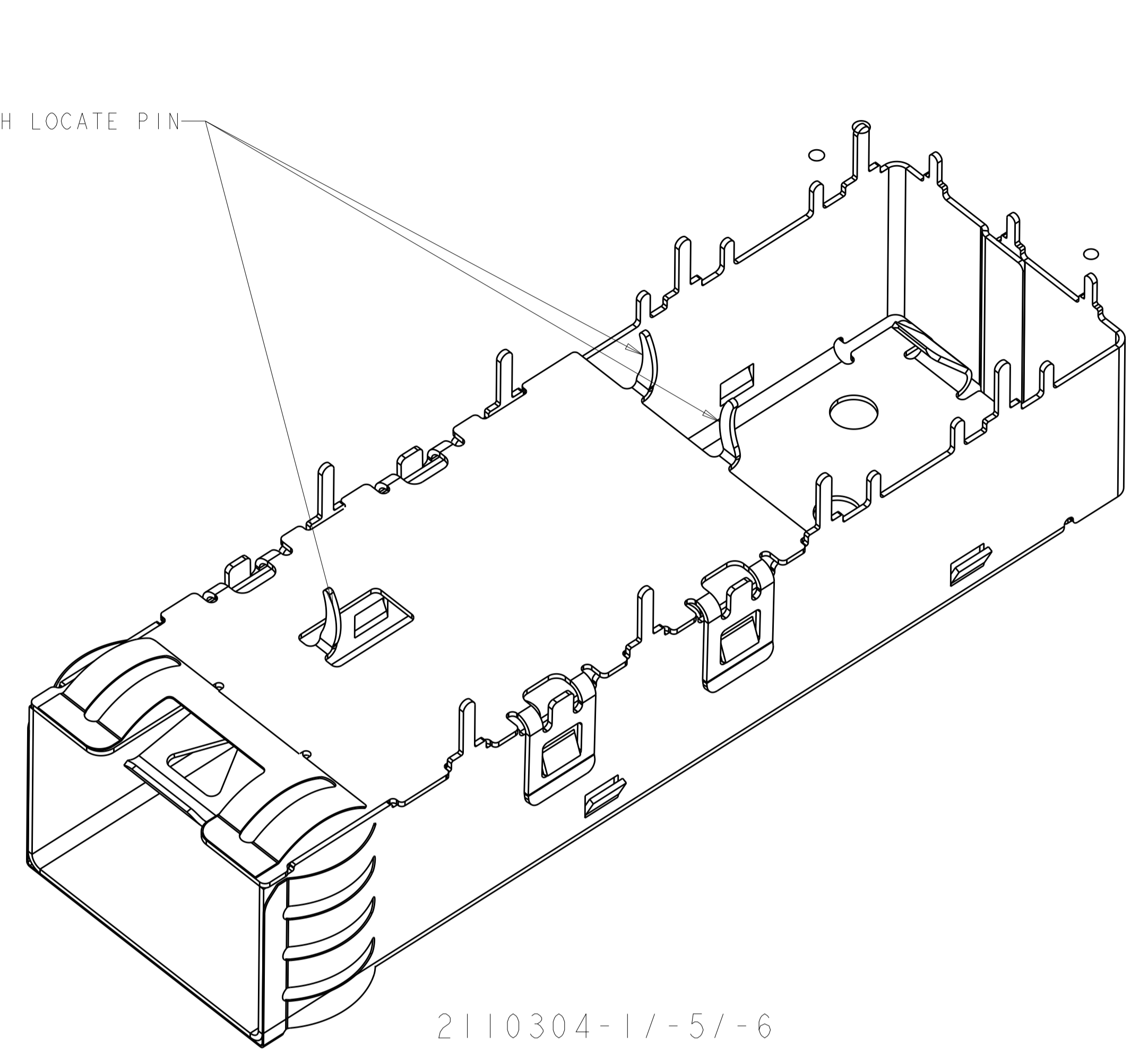
STE TE Connectivity

NAME: SFP+ IXI CAGE ASSEMBLY, SOLDER TAIL, EMI SPRINGS

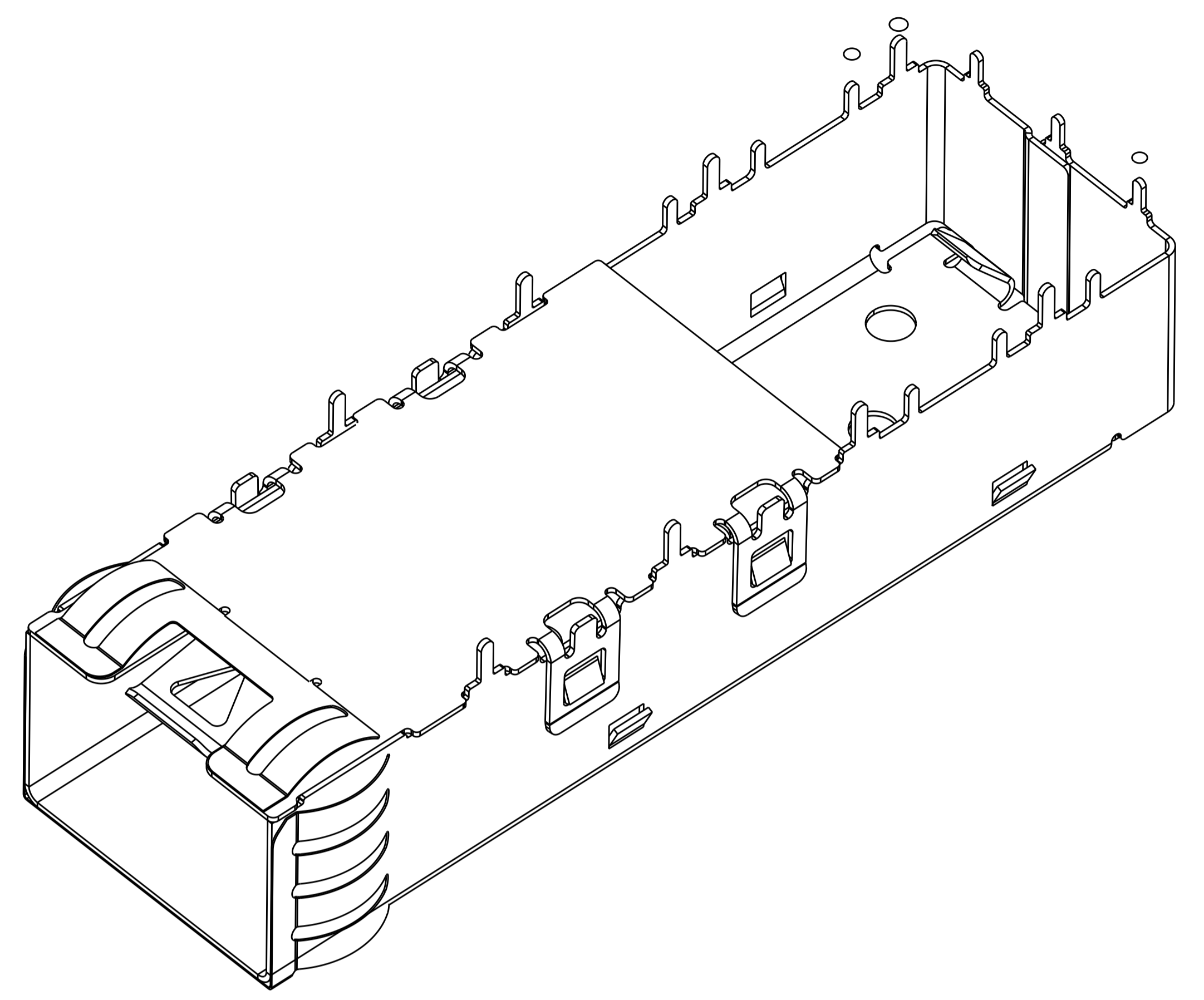
SIZE: A1 CAGE CODE: 2110304 DRAWING NO: 100779

LOC	DIST	REVISIONS			
P.	LYR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-

WITH LOCATE PIN

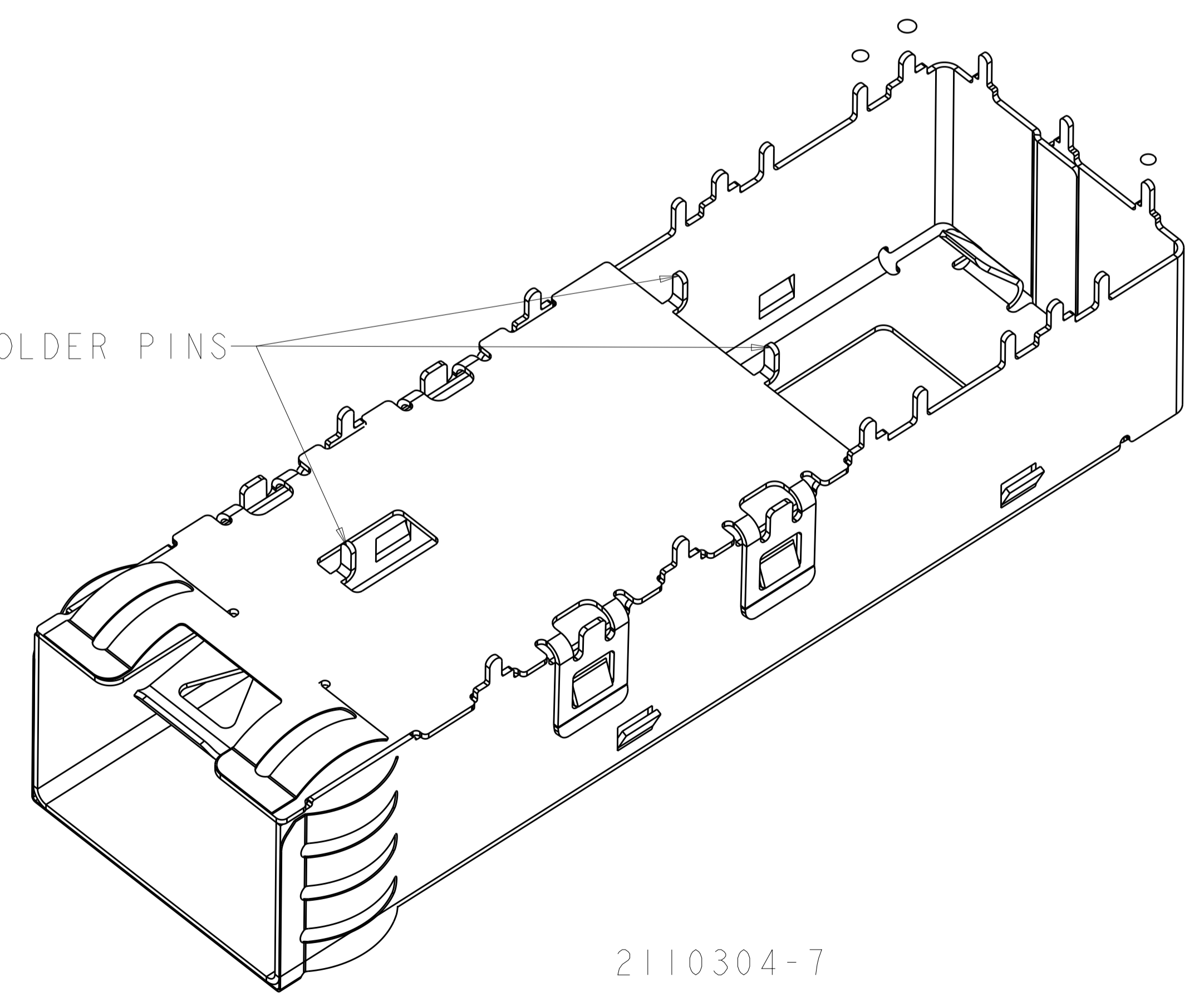


2110304-1/-5/-6



2110304-3/-8

WITH SOLDER PINS

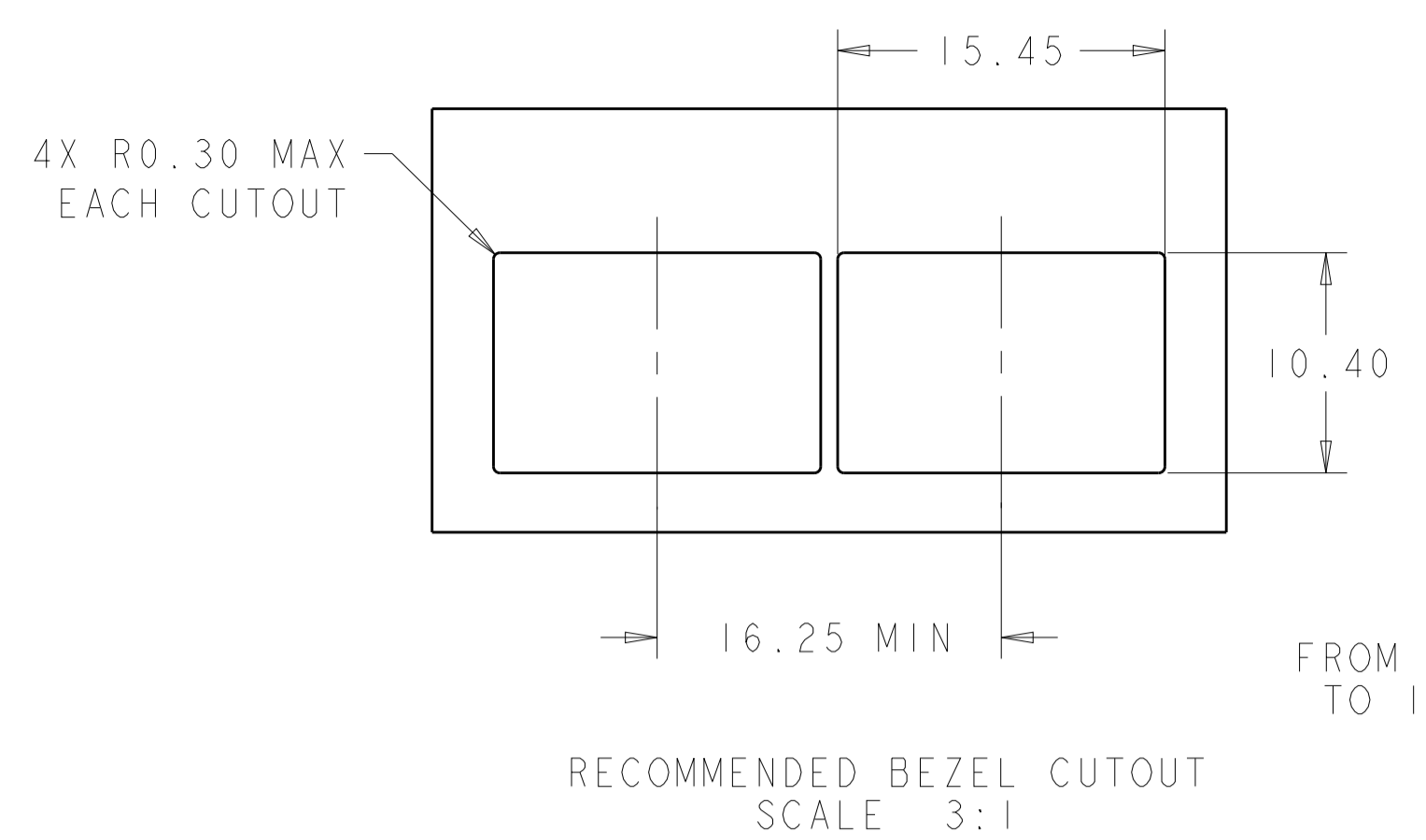


2110304-7

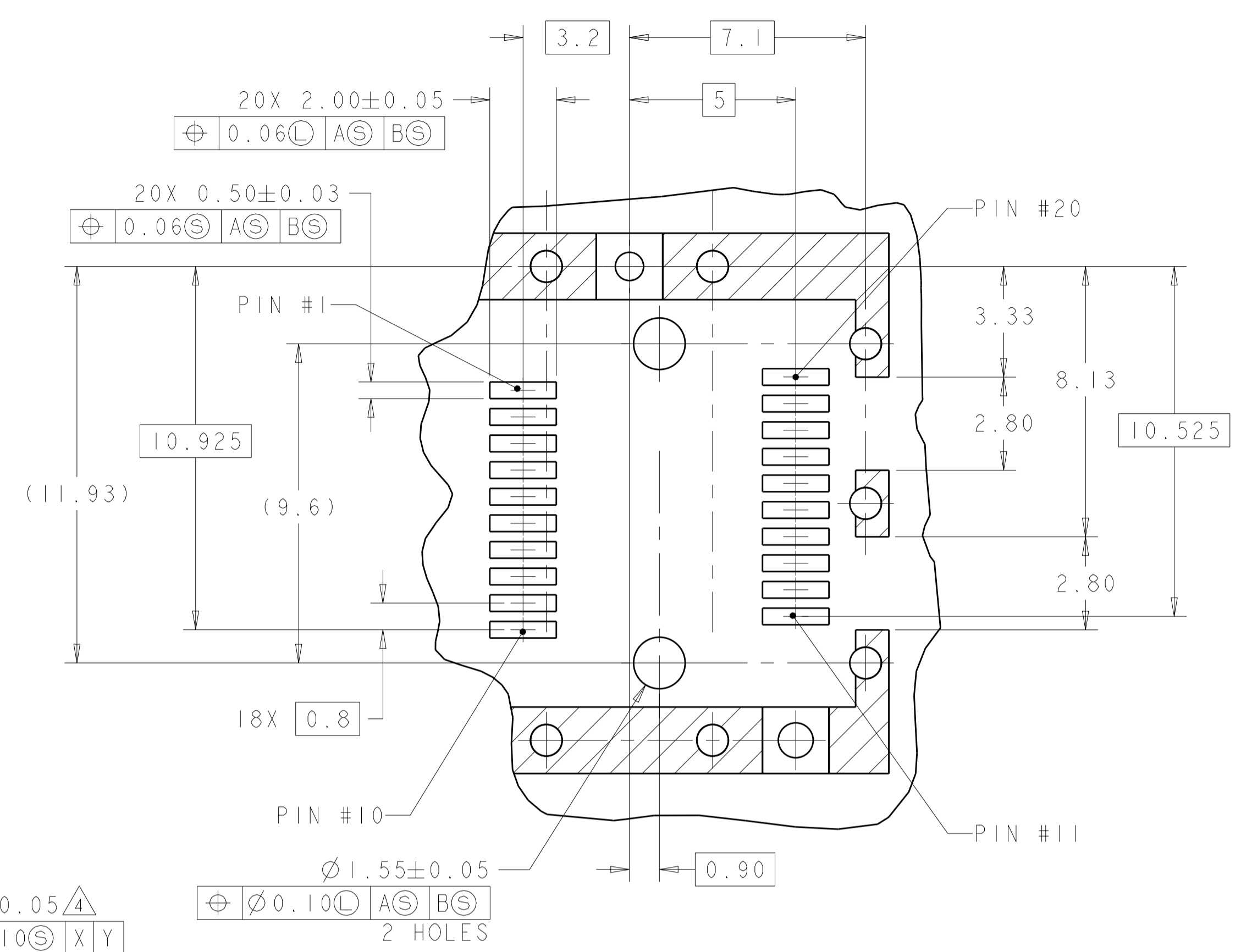
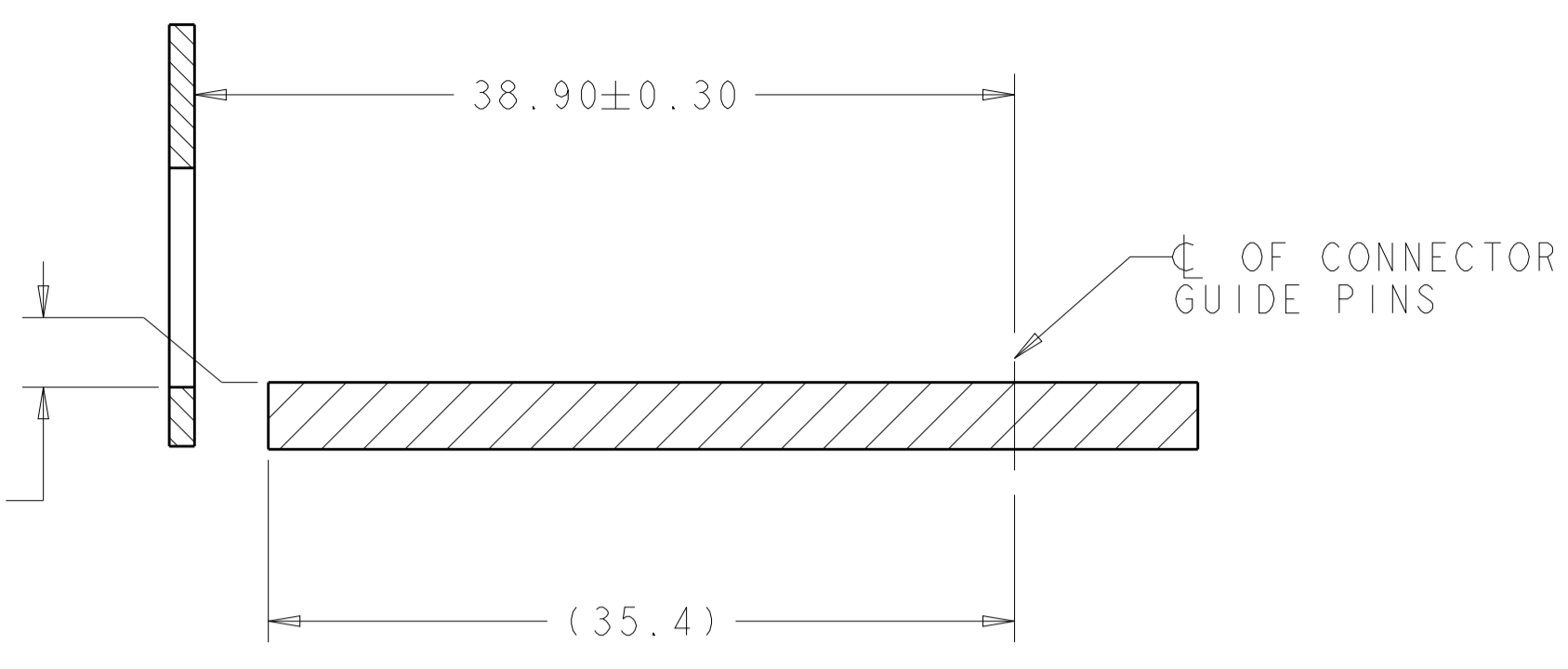
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN C. ROHLER 13FEB2009	TE Connectivity
DIMENSIONS:		CHK M. SCHMITT 13FEB2009	
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD B. WERTZ 13FEB2009	NAME SFP+ IXI CAGE ASSEMBLY, SOLDER TAIL, EMI SPRINGS
	0 PLC ±0.1 1 PLC ±0.5 2 PLC ±0.5 3 PLC ±0.5 4 PLC ±0.13 ANGLES ±0.13 FINISH -	PRODUCT SPEC	SIZE 114-13120
MATERIAL	FINISH	APPLICATION SPEC	RESTRICTED TO
-	-	WEIGHT	A100779C=2110304
Customer Drawing		SCALE 1:1	SHEET 2 OF 4 REV D4

LOC	DIST	REV	DATE	BY	APPV
GP	00				

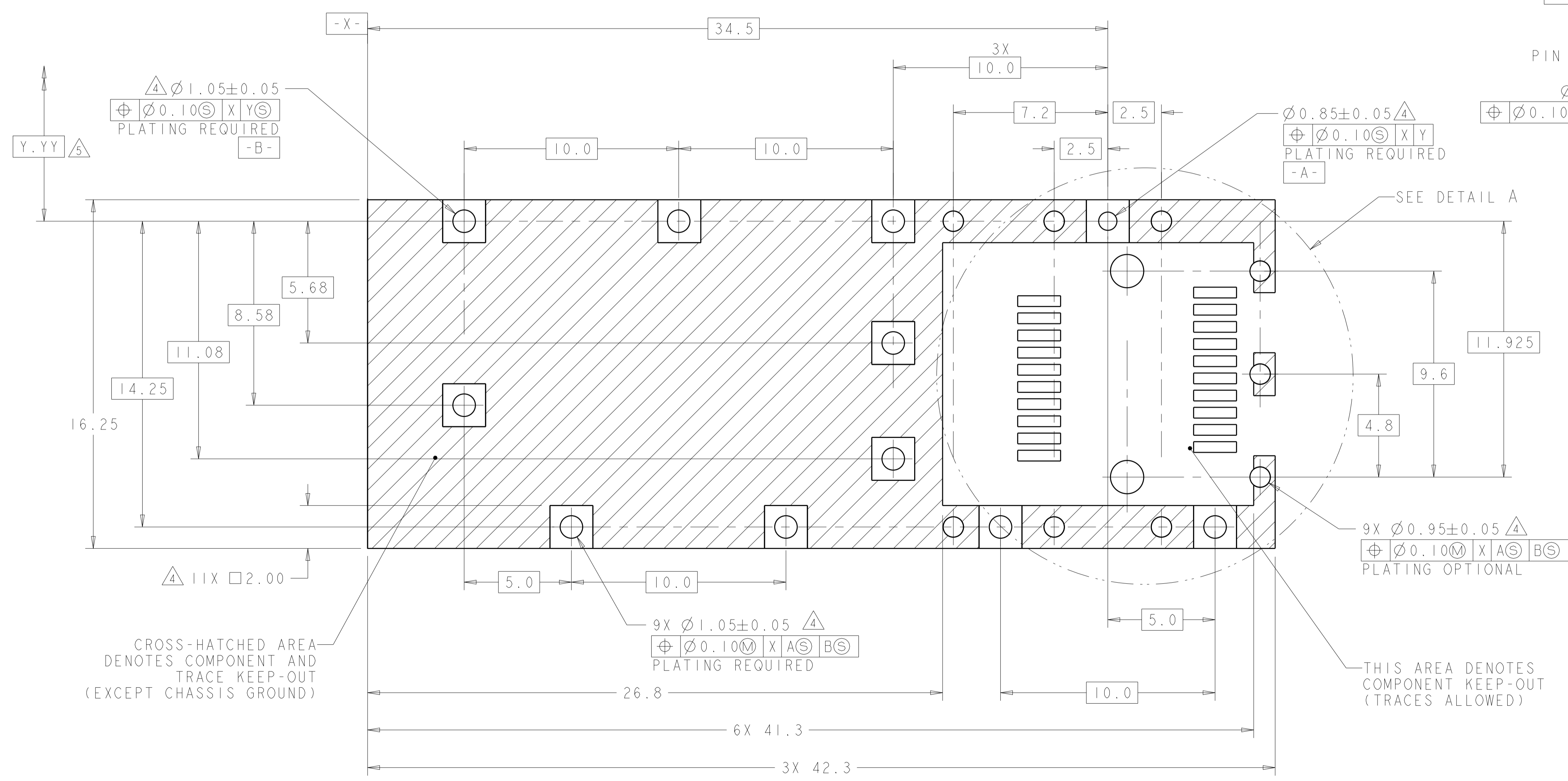
REVISIONS		DATE	BY	APPV
1	SEE SHEET 1			



0.23^{+0.10}_{-0.14}
 FROM THE TOP OF PCB
 TO INSIDE OF BEZEL
 CUT-OUT



DETAIL A
 SCALE 8:1



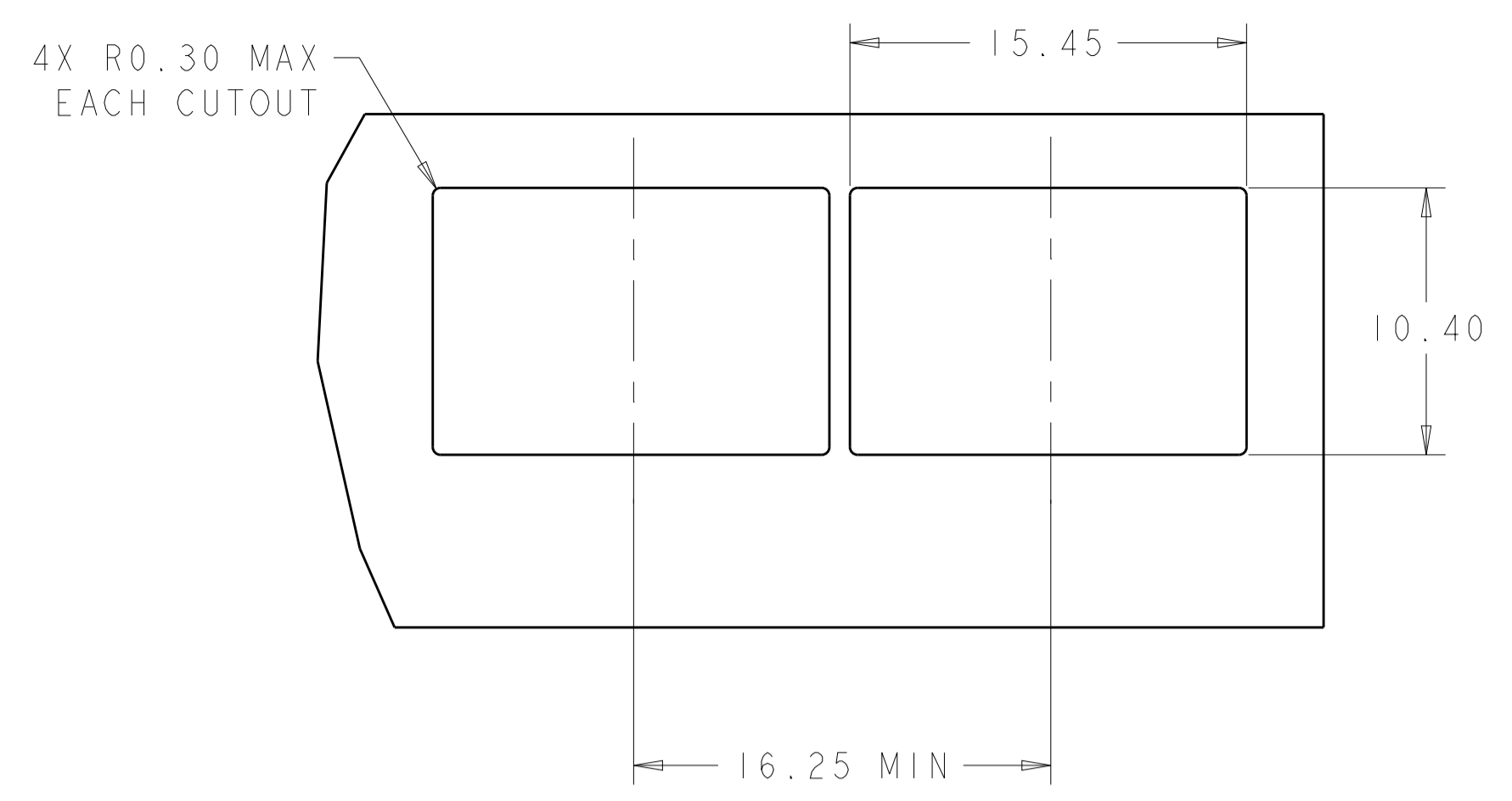
CROSS-HATCHED AREA
 DENOTES COMPONENT AND
 TRACE KEEP-OUT
 (EXCEPT CHASSIS GROUND)

THIS AREA DENOTES
 COMPONENT KEEP-OUT
 (TRACES ALLOWED)

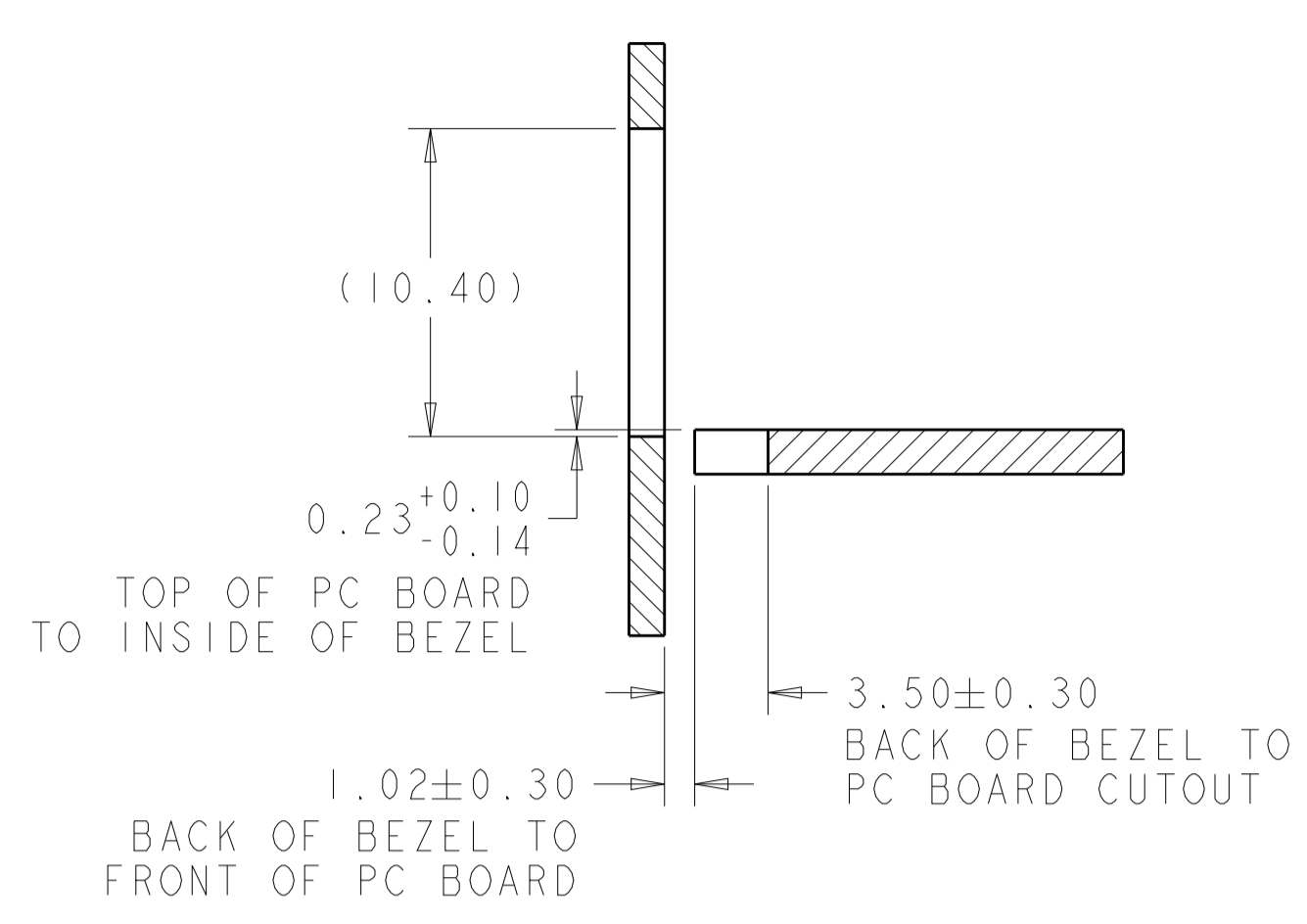
2110304-1/-5/-6/-7
 RECOMMENDED PCB LAYOUT
 SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN C. ROHLER 13FEB2009	TE Connectivity
DIMENSIONS:		CHK M. SCHMITT 13FEB2009	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APV B. WERTZ 13FEB2009	NAME SFP+ IXI CAGE ASSEMBLY, SOLDER TAIL, EMI SPRINGS
mm	0 PLC ±0.1 1 PLC ±0.5 2 PLC ±0.5 3 PLC ±0.13 4 PLC ±0.13 ANGLES ±0.13	PRODUCT SPEC	SIZE 114-13120
MATERIAL	FINISH	APPLICATION SPEC	RESTRICTED TO
		WEIGHT	A100779C=2110304
		Customer Drawing	SCALE 1:1 SHEET 3 OF 4 REV D4

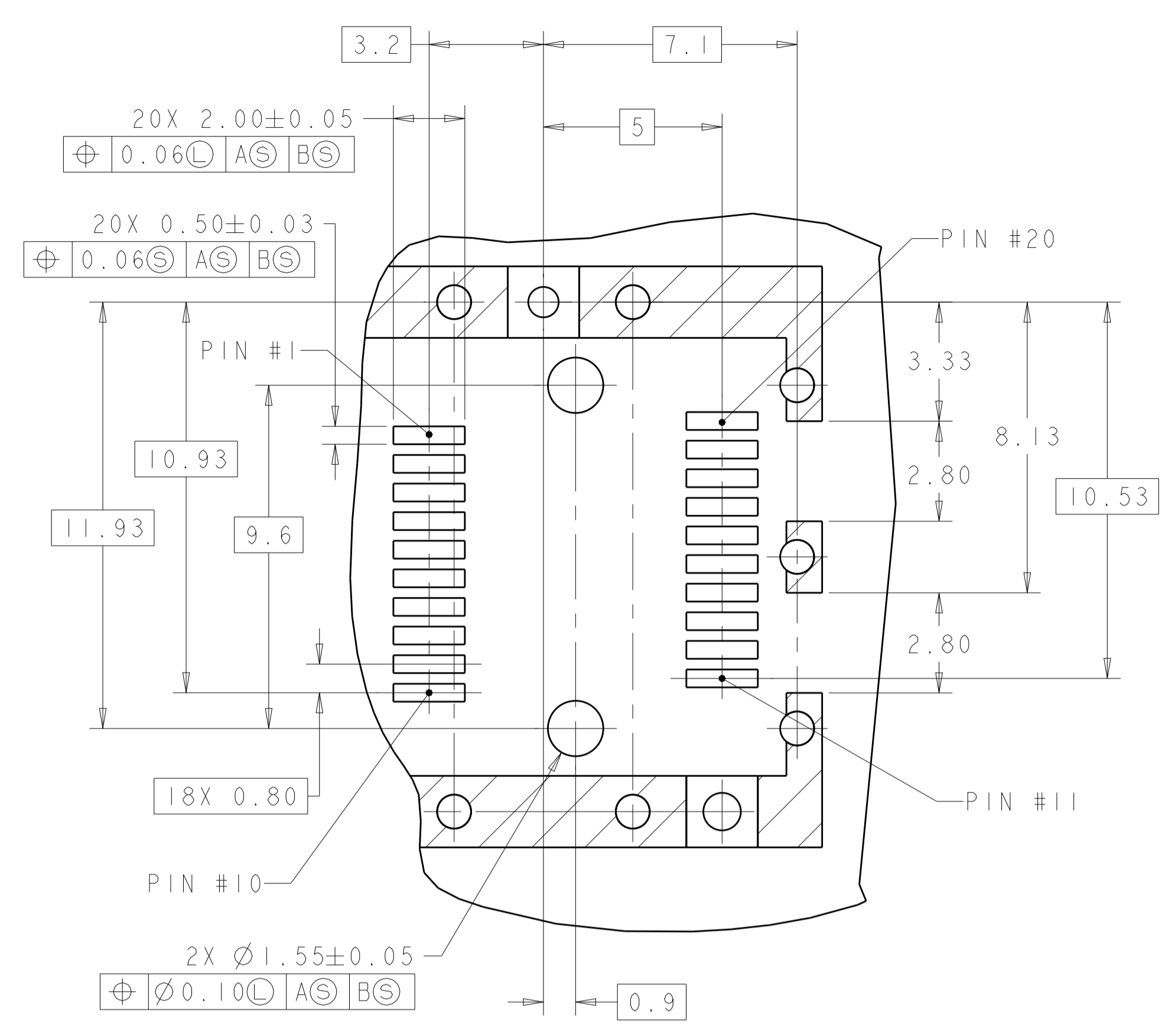
LOC	DIST	REV	DATE	BY	APPV
GP	00	-	-	-	-
REVISIONS			DESCRIPTION		
-			SEE SHEET 1		



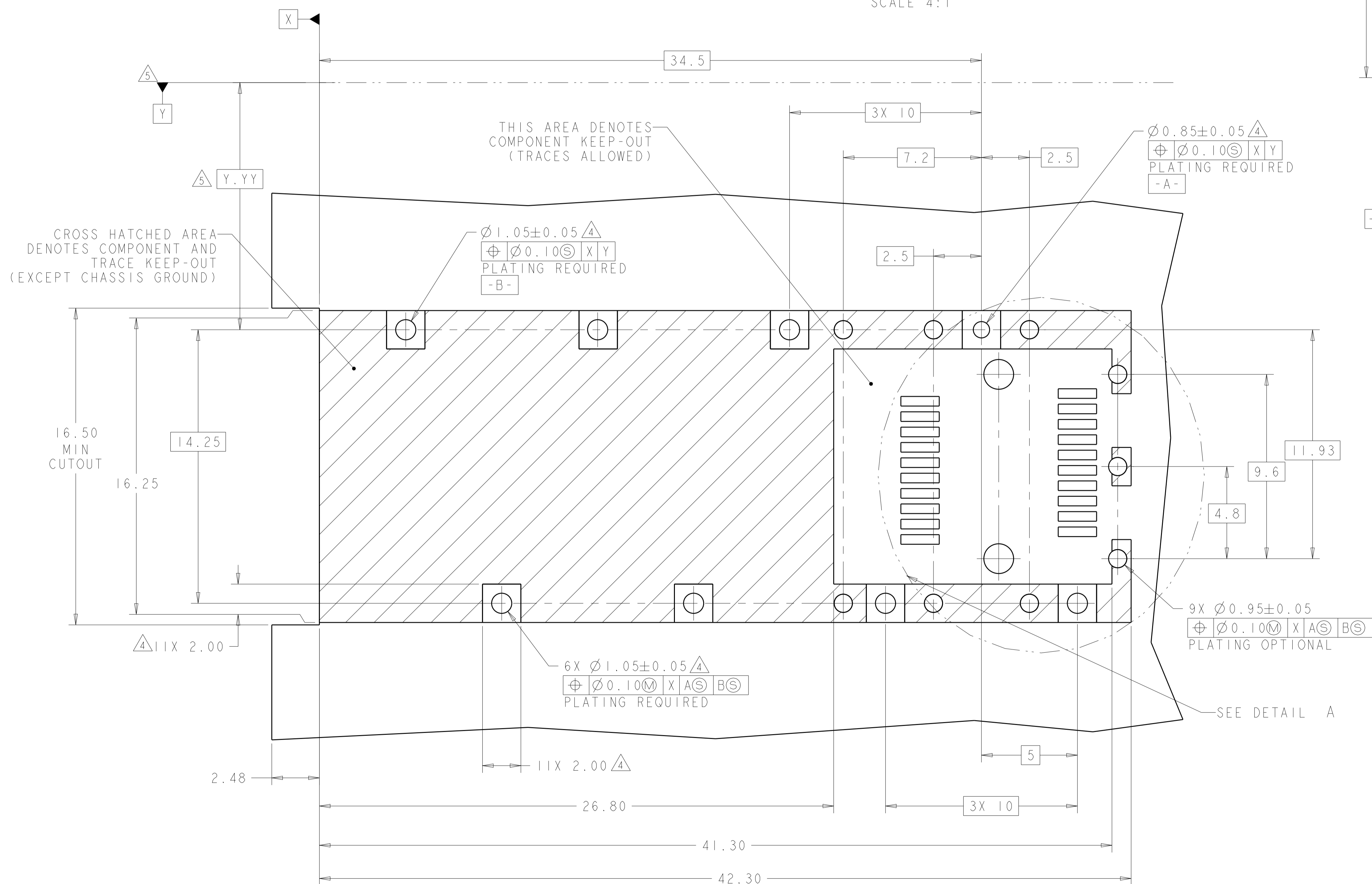
RECOMMENDED BEZEL CUTOUT
SCALE 4:1



RECOMMENDED BEZEL AND
PC BOARD ORIENTATION
SCALE 4:1



DETAIL A
SCALE 8:1



2110304-3/-8
RECOMMENDED PCB LAYOUT
SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN C. ROHLER CHK M. SCHMITT	13FEB2009 13FEB2009	STE TE Connectivity	
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APV B. WERTZ	13FEB2009	NAME SFP+ 1XI CAGE ASSEMBLY, SOLDER TAIL, EMI SPRINGS	
mm	0 PLC ±0.1 1 PLC ±0.5 2 PLC ±0.5 3 PLC ±0.13 4 PLC ±0.13 ANGLES ±0.13	PRODUCT SPEC		SIZE	CAGE CODE DRAWING NO
MATERIAL	FINISH	APPLICATION SPEC	114-13120	A100779	C=2110304
		WEIGHT		Customer Drawing	SCALE 2:1 SHEET 4 OF 4 REV D4